

100V PNP MEDIUM POWER TRANSISTOR IN SOT223

Features

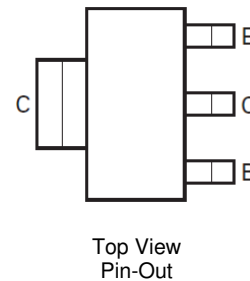
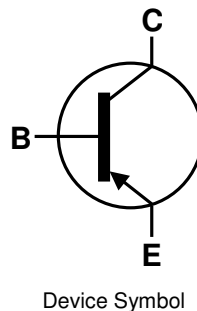
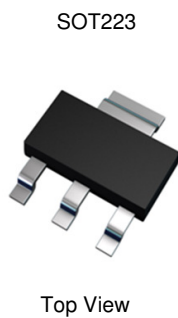
- $BV_{CEO} > -100V$
- $I_C = -5A$ High Continuous Collector Current
- $I_{CM} = -10A$ Peak Pulse Current
- Low Saturation Voltage $V_{CE(sat)} < -90mV @ -1A$
- $R_{SAT} = 60m\Omega$ for a Low equivalent On-Resistance
- h_{FE} Specified up to -10A for a High Gain Hold-Up
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound; UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.112 grams (Approximate)

Applications

- Motor Driving
- Line Switching
- High Side Switches
- Subscriber Line Interface Cards (SLIC)

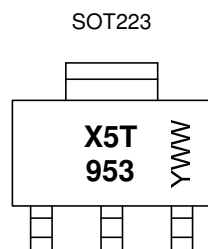


Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZX5T953GTA	AEC-Q101	X5T953	7	12	1,000
ZX5T953GQTA	Automotive	X5T953	7	12	1,000

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



X5T953 = Product Type Marking Code
 YWW = Date Code Marking
 Y or \bar{Y} = Last Digit of Year (ex: 5= 2015)
 WW or $\bar{W}W$ = Week Code (01~53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	-140	V
Collector-Emitter Voltage	V _{CEO}	-100	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	I _C	-5	A
Peak Pulse Current	I _{CM}	-10	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

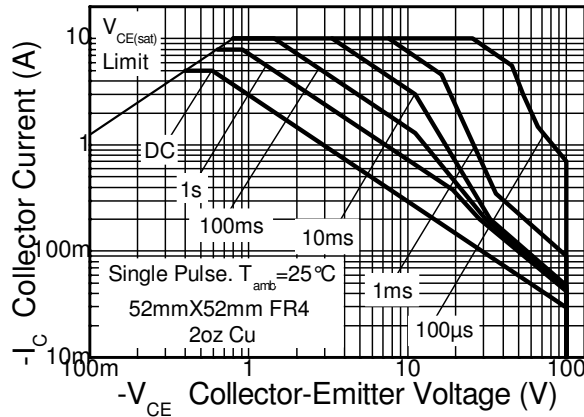
Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	3.0	W
		24	
Linear Derating Factor		1.6	mW / °C
		12.8	
Thermal Resistance, Junction to Ambient	R _{θJA} (Note 6)	42	°C/W
	R _{θJA} (Note 7)	78	
Thermal Resistance Junction to Lead	R _{θJL} (Note 8)	10.4	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 9)

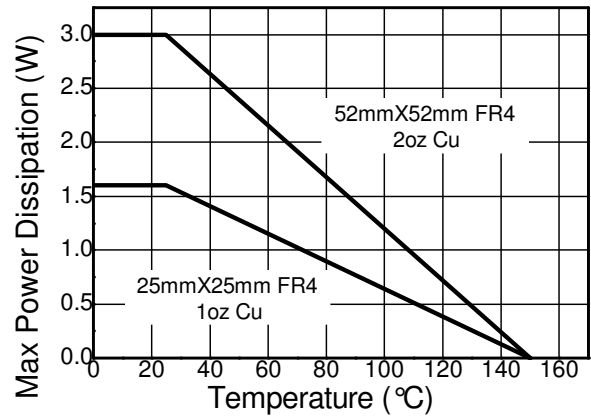
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the collector lead on 52mm x 52mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 7. Same as Note 5, except the device is mounted on 25mm x 25mm 1oz copper.
 8. Thermal resistance from junction to solder-point (at the end of the collector lead).
 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

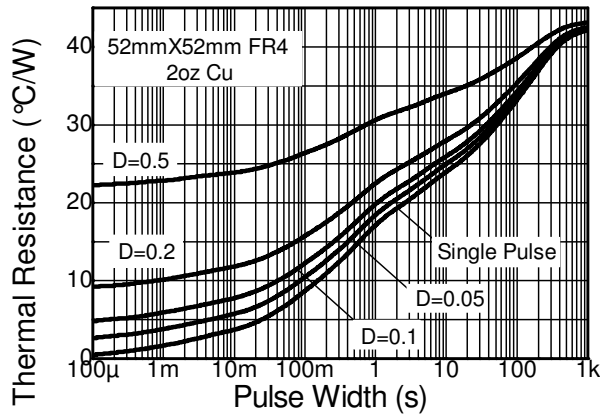
Thermal Characteristics and Derating Information



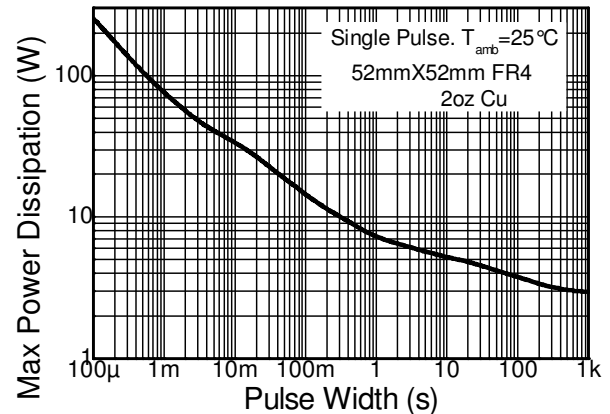
Safe Operating Area



Derating Curve



Transient Thermal Impedance



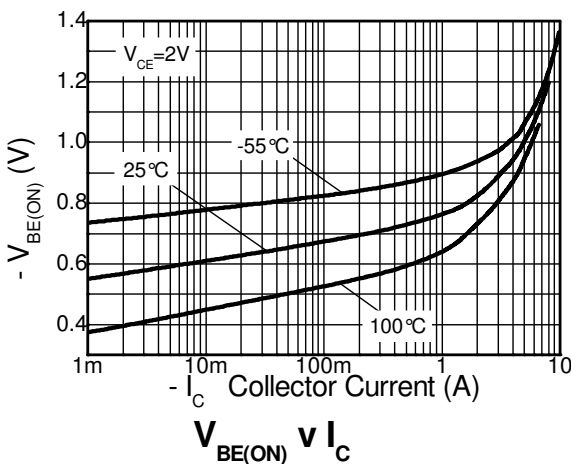
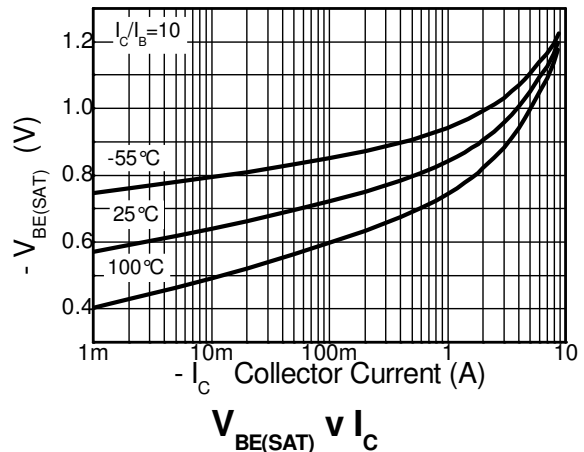
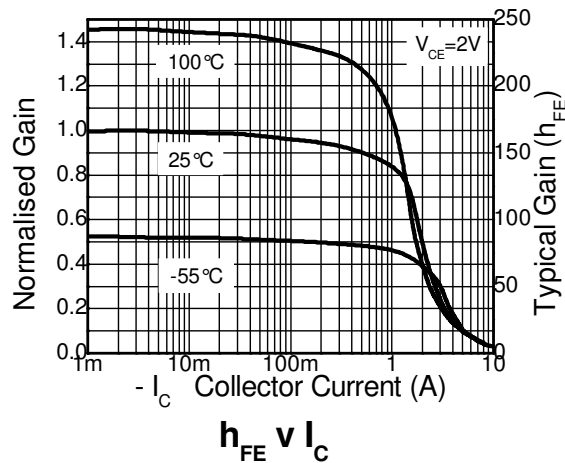
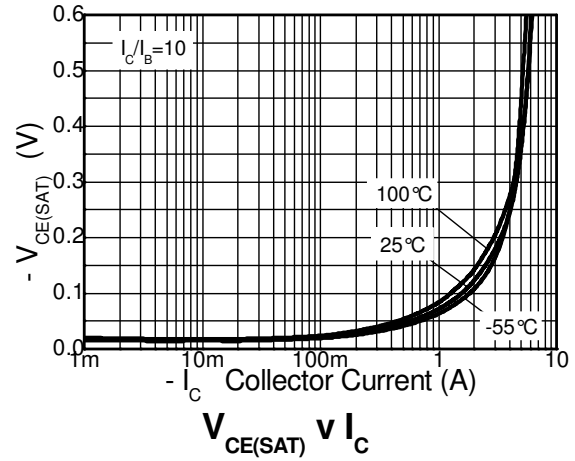
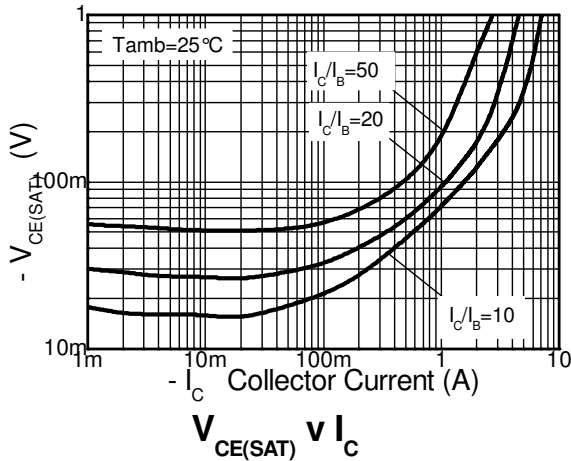
Pulse Power Dissipation

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	-140	-160	-	V	$I_C = -100\mu\text{A}$
Collector-Emitter Breakdown Voltage	BV_{CER}	-140	-160	-	V	$I_C = -1\mu\text{A}$, $R_B \leq 1\text{k}\Omega$
Collector-Emitter Breakdown Voltage (Note 10)	BV_{CEO}	-100	-115	-	V	$I_C = -1\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	-7	-8.1	-	V	$I_E = -100\mu\text{A}$
Collector-Base Cut-Off Current	I_{CBO}	-	<1	-20	nA	$V_{CB} = -100\text{V}$
				-0.5	μA	$V_{CB} = -100\text{V}$, $T_A = +100^\circ\text{C}$
Collector-Emitter Cut-Off Current	I_{CER} $R \leq 1\text{k}\Omega$	-	<1	-20	nA	$V_{CB} = -100\text{V}$
				-0.5	μA	$V_{CB} = -100\text{V}$, $T_A = +100^\circ\text{C}$
Emitter Cut-Off Current	I_{EBO}	-	<1	-10	nA	$V_{EB} = -6\text{V}$
Static Forward Current Transfer Ratio (Note 10)	h_{FE}	100	250	-	-	$I_C = -10\text{mA}$, $V_{CE} = -1\text{V}$
		100	200	300		$I_C = -1\text{A}$, $V_{CE} = -1\text{V}$
		25	50	-		$I_C = -3\text{A}$, $V_{CE} = -1\text{V}$
		15	30	-		$I_C = -4\text{A}$, $V_{CE} = -1\text{V}$
		-	5	-		$I_C = -10\text{A}$, $V_{CE} = -1\text{V}$
Collector-Emitter Saturation Voltage (Note 10)	$V_{CE(sat)}$	-	-20	-30	mV	$I_C = -100\text{mA}$, $I_B = -10\text{mA}$
		-	-70	-90		$I_C = -1\text{A}$, $I_B = -100\text{mA}$
		-	-120	-150		$I_C = -2\text{A}$, $I_B = -200\text{mA}$
		-	-240	-340		$I_C = -4\text{A}$, $I_B = -400\text{mA}$
Base-Emitter Saturation Voltage (Note 10)	$V_{BE(sat)}$	-	-985	-1100	mV	$I_C = -4\text{A}$, $I_B = -400\text{mA}$
Base-Emitter Turn-On Voltage (Note 10)	$V_{BE(on)}$	-	-920	-1050	mV	$I_C = -4\text{A}$, $V_{CE} = -2\text{V}$
Output Capacitance (Note 10)	C_{obo}	-	42	-	pF	$V_{CB} = -10\text{V}$, $f = 1\text{MHz}$
Transition Frequency	f_T	-	125	-	MHz	$V_{CE} = -10\text{V}$, $I_C = -100\text{mA}$ $f = 50\text{MHz}$
Switching Time	t_{on}	-	42	-	ns	$V_{CC} = -10\text{V}$, $I_C = -1\text{A}$ $I_{B1} = I_{B2} = -100\text{mA}$
	t_{off}	-	540	-		

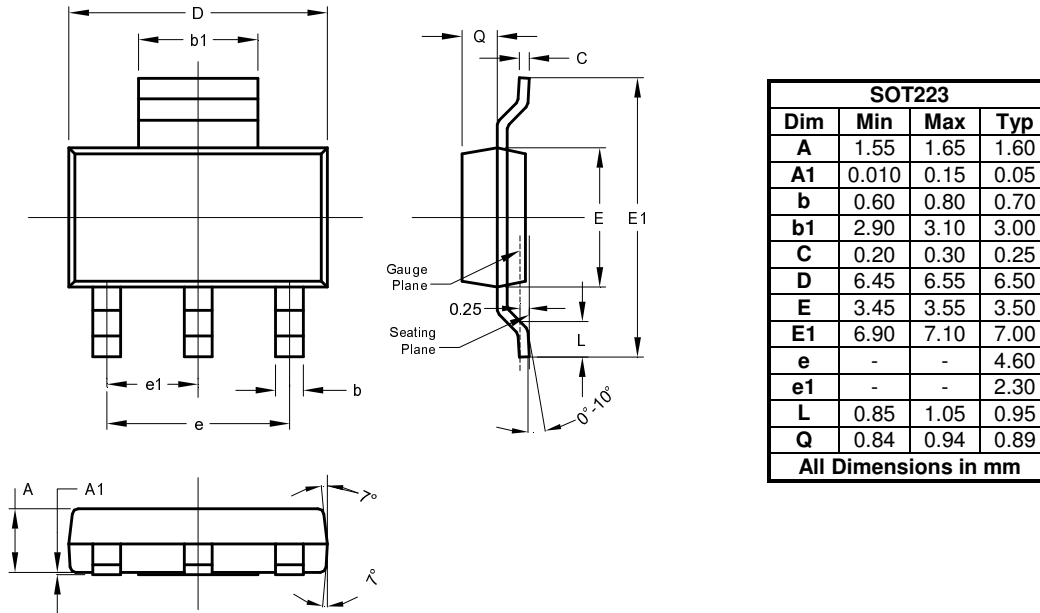
Note: 10. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



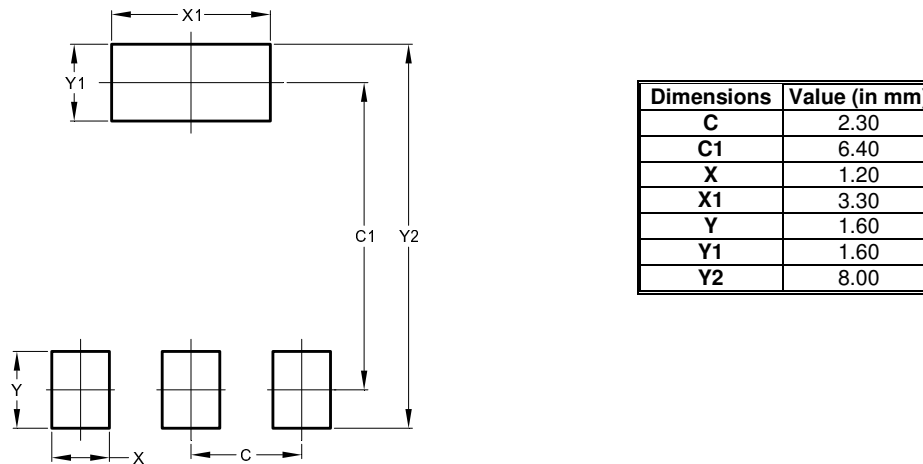
Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.

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